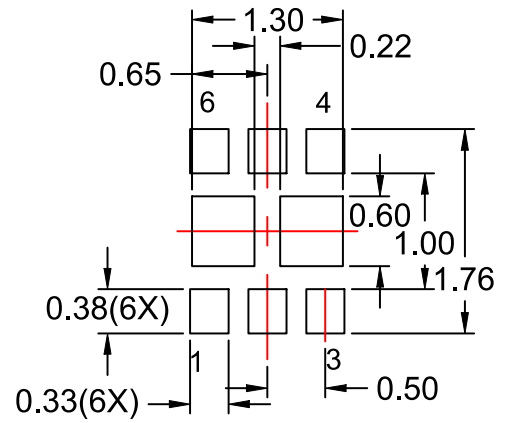
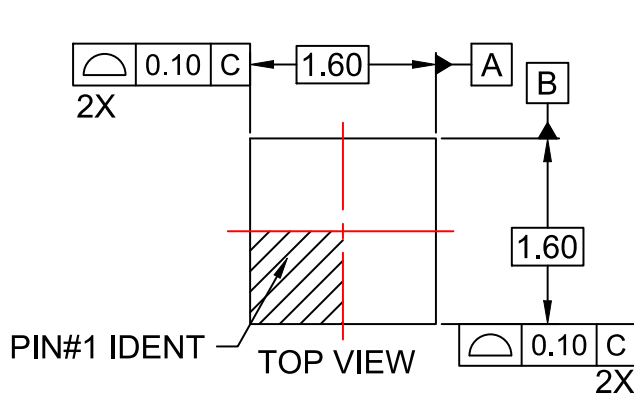
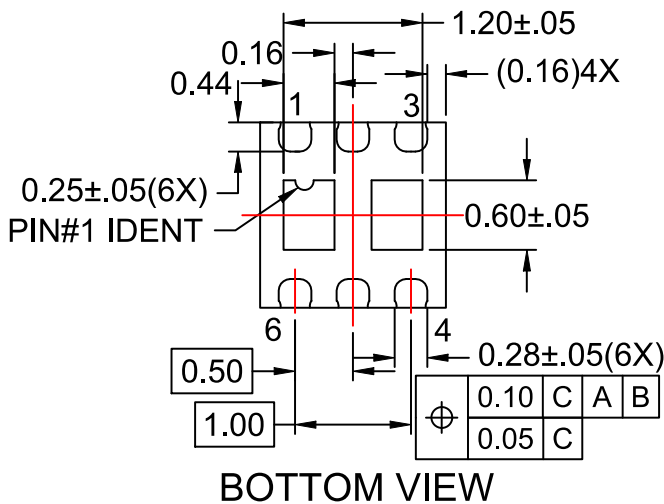
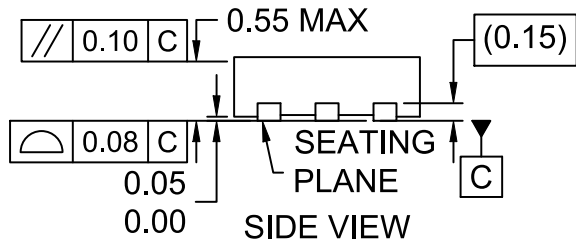


**UDFN6 1.6x1.6, 0.5P**  
CASE 517DW  
ISSUE 0

DATE 31 OCT 2016



**RECOMMENDED  
LAND PATTERN**



**NOTES:**

- A. PACKAGE DOES NOT CONFORM TO ANY JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

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